

BE BOP

TO THE

Boolean Boogie

Second Edition

An Unconventional Guide to Electronics



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PLUS BONUS CHAPTER *An Illustrated History of Electronics and Computing*

Clive "Max" Maxfield



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**BEBOP
TO THE** **B**OOLEAN
BOOGIE

Second Edition

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BOOLEAN BOOGIE

*An unconventional guide to electronics
fundamentals, components, and processes*

by Clive (call me “Max”) Maxfield

Foreword by Pete Waddell,
Publisher of *Printed Circuit Design*



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Foreword

My first exposure to the unique writing style of Clive (call me “Max”) Maxfield was a magazine article that he co-wrote with an associate. The article was technically brilliant (he paid me to say that) and very informative, but it was the short biography at the end of the piece that I enjoyed the most. I say enjoyed the most because, as you will soon learn, Max does not necessarily follow the herd or dance to the same drummer as the masses. Trade journals have a reputation for being informative and educational but also as dry as West Texas real estate.

Anyway, Max’s personally submitted biography not only included a message from his mom, but also made mention of the fact that he (Max) is taller than his co-author, who just happened to be his boss at the time. Now to some people this may seem irrelevant, but to our readers (and Max’s boss), these kind of things—trivial as they may seem to the uninitiated—are what helps us to maintain our off-grid sense of the world. Max has become, for better or worse, a part of that alternate life experience.

So now it’s a couple of years later, and Max has asked me to write a few words by way of introduction. Personally, I think that the title of this tome alone (hmmm, a movie?) should provide some input as to what you can expect. But, for those who require a bit more: be forewarned, dear reader, you will probably learn far more than you could hope to expect from *Bebop to the Boolean Boogie*, just because of the unique approach Max has to technical material. The author will guide you from the basics through a minefield of potentially boring theoretical mish-mash, to a Nirvana of understanding. You will not suffer that fate familiar to every reader: rereading paragraphs over and over wondering what in the world the author was trying to say. For a limey, Max shoots amazingly well and from the hip, but in a way that will keep you interested and amused. If you are not vigilant, you may not only learn something, but you may even enjoy the process. The only further advice I can give is to “expect the unexpected.”

— PETE WADDELL, Publisher, *Printed Circuit Design*
Literary genius (so says his mom), and taller than Max by 1/8"

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